



LET21004

RF POWER TRANSISTORS

Ldmos Enhanced Technology in Plastic Package

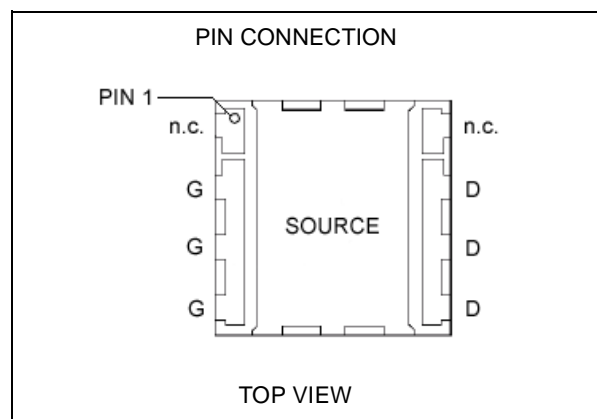
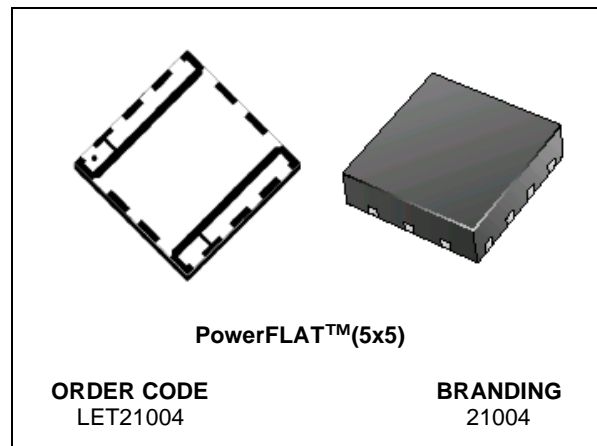
TARGET DATA

Designed for GSM / EDGE / IS-97 / WCDMA applications

- EXCELLENT THERMAL STABILITY
- COMMON SOURCE CONFIGURATION
- $P_{OUT} = 4\text{ W}$ with 11 dB gain @ 2170 MHz / 26 V
- NEW LEADLESS PLASTIC PACKAGE
- ESD PROTECTION

DESCRIPTION

The LET21004 is a common source N-Channel, enhancement-mode lateral Field-Effect RF power transistor. It is designed for high gain, broad band commercial and industrial applications. It operates at 26 V in common source mode at frequencies up to 2.1 GHz. LET21004 boasts the excellent gain, linearity and reliability of ST's latest LDMOS technology mounted in the innovative leadless SMD plastic package, PowerFLAT™. LET21004's superior linearity performance makes it an ideal solution for base station applications.



ABSOLUTE MAXIMUM RATINGS ($T_{CASE} = 25\text{ }^{\circ}\text{C}$)

| Symbol | Parameter | Value | Unit |
|---------------|---|-------------|--------------------|
| $V_{(BR)DSS}$ | Drain-Source Voltage | 65 | V |
| V_{GS} | Gate-Source Voltage | -0.5 to +15 | V |
| I_D | Drain Current | 1 | A |
| P_{DISS} | Power Dissipation (@ $T_c = 70\text{ }^{\circ}\text{C}$) | TBD | W |
| T_j | Max. Operating Junction Temperature | 150 | $^{\circ}\text{C}$ |
| T_{STG} | Storage Temperature | -65 to +150 | $^{\circ}\text{C}$ |

THERMAL DATA ($T_{CASE} = 70\text{ }^{\circ}\text{C}$)

| | | | |
|---------------|-----------------------------------|-----|----------------------|
| $R_{th(j-c)}$ | Junction -Case Thermal Resistance | TBD | $^{\circ}\text{C/W}$ |
|---------------|-----------------------------------|-----|----------------------|

ELECTRICAL SPECIFICATION ($T_{CASE} = 25\text{ }^{\circ}\text{C}$)**STATIC**

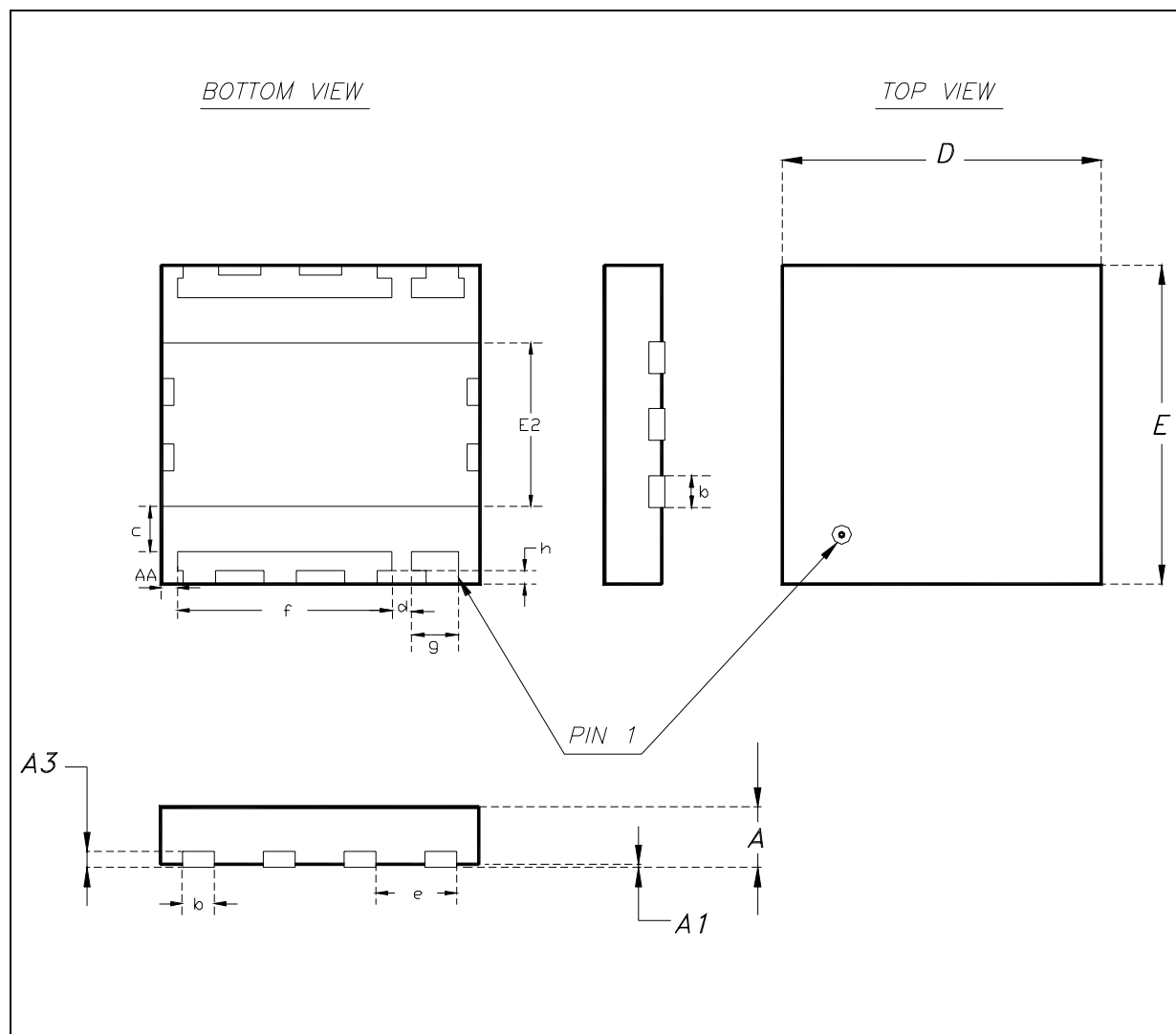
| Symbol | Test Conditions | | Min. | Typ. | Max. | Unit |
|---------------|------------------------|------------------------|------|------|------|---------------|
| $V_{(BR)DSS}$ | $V_{GS} = 0\text{ V}$ | $I_{DS} = 1\text{ mA}$ | 65 | | | V |
| I_{DSS} | $V_{GS} = 0\text{ V}$ | $V_{DS} = 26\text{ V}$ | | | 1 | μA |
| I_{GSS} | $V_{GS} = 5\text{ V}$ | $V_{DS} = 0\text{ V}$ | | | 1 | μA |
| $V_{GS(Q)}$ | $V_{DS} = 28\text{ V}$ | $I_D = \text{TBD}$ | 2.5 | | 5.0 | V |
| $V_{DS(ON)}$ | $V_{GS} = 10\text{ V}$ | $I_D = 0.3\text{ A}$ | | TBD | 0.3 | V |
| G_{FS} | $V_{DS} = 10\text{ V}$ | $I_D = 0.3\text{ A}$ | | TBD | | mho |
| C_{ISS} | $V_{GS} = 0\text{ V}$ | $V_{DS} = 26\text{ V}$ | | TBD | | pF |
| C_{OSS} | $V_{GS} = 0\text{ V}$ | $V_{DS} = 26\text{ V}$ | | TBD | | pF |
| C_{RSS} | $V_{GS} = 0\text{ V}$ | $V_{DS} = 26\text{ V}$ | | TBD | | pF |

| Symbol | Test Conditions | Min. | Typ. | Max. | Unit |
|---------------------------------|---|------|------|------|------|
| DYNAMIC (f = 2170 MHz) | | | | | |
| P _{out} ⁽¹⁾ | V _{DD} = 26 V I _{DQ} = TBD | 4 | 5 | | W |
| η _D ⁽¹⁾ | V _{DD} = 26 V I _{DQ} = TBD | 45 | 50 | | % |
| Load mismatch | V _{DD} = 26 V I _{DQ} = TBD P _{OUT} = 4 W ALL PHASE ANGLES | | | 10:1 | VSWR |
| DYNAMIC (f = 2110 - 2170 MHz) | | | | | |
| P _{out} ⁽¹⁾ | V _{DD} = 26 V I _{DQ} = TBD | 3 | 4 | | W |
| η _D ⁽¹⁾ | V _{DD} = 26 V I _{DQ} = TBD | 40 | 45 | | % |
| G _P | V _{DD} = 26 V I _{DQ} = TBD P _{OUT} = 4 W | 11 | 13 | | dB |
| P _{OUT(W-CDMA)} | ACPR: -45dBc | | 1 | | W |
| η _{D(W-CDMA)} | ACPR: -45dBc | | 25 | | % |

(1) 1 dB Compression point

PowerFLAT™ MECHANICAL DATA

| DIM. | mm | | | Inch | | |
|------|------|------|------|-------|-------|-------|
| | MIN. | TYP. | MAX | MIN. | TYP. | MAX |
| A | | 0.90 | 1.00 | | 0.035 | 0.039 |
| A1 | | 0.02 | 0.05 | | 0.001 | 0.002 |
| A3 | | 0.24 | | | 0.009 | |
| AA | 0.15 | 0.25 | 0.35 | 0.006 | 0.01 | 0.014 |
| b | 0.43 | 0.51 | 0.58 | 0.017 | 0.020 | 0.023 |
| c | 0.64 | 0.71 | 0.79 | 0.025 | 0.028 | 0.031 |
| D | | 5.00 | | | 0.197 | |
| d | | 0.30 | | | 0.011 | |
| E | | 5.00 | | | 0.197 | |
| E2 | 2.49 | 2.57 | 2.64 | 0.098 | 0.101 | 0.104 |
| e | | 1.27 | | | 0.050 | |
| f | | 3.37 | | | 0.132 | |
| g | | 0.74 | | | 0.03 | |
| h | | 0.21 | | | 0.008 | |



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